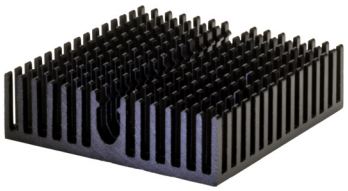
MODEL: HSB36-353510 | DESCRIPTION: HEAT SINK

FEATURES

- BGA design
- low profile
- aluminum alloy
- black anodized finish



RoHS

MODEL

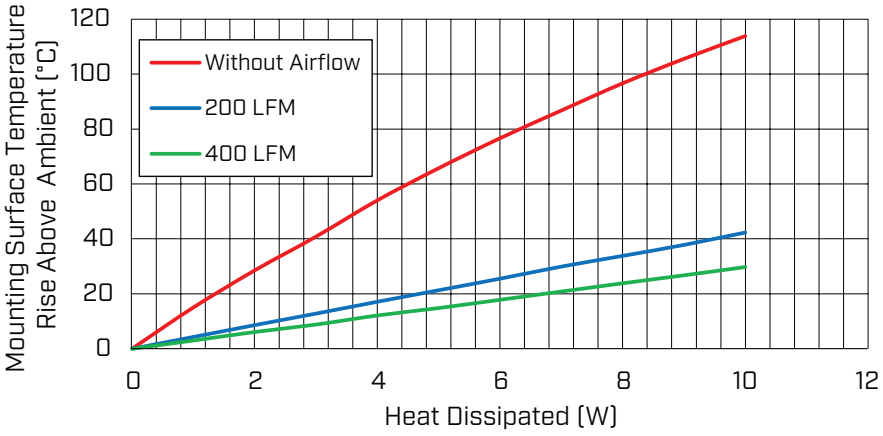
MODEL	thermal resistance[1] @ 75°C ΔT, nat conv (°C/W)	@ 1 W, nat conv (°C/W)	@ 1 W, 200 LFM (°C/W)	@ 1 W, 400 LFM (°C/W)	power dissipation[1] @ 75°C ΔT, nat conv (W)
HSB36-353510	12.72	15.0	4.3	3.0	5.90

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	15.0	4.3	3.0
2	28.5	8.6	6.1
3	40.8	12.8	8.8
4	54.0	17.1	12.1
5	65.7	21.3	14.8
6	76.6	25.5	17.8
7	86.7	29.9	20.8
8	96.6	33.8	23.8
9	105.5	37.8	26.7
10	113.8	42.3	29.7

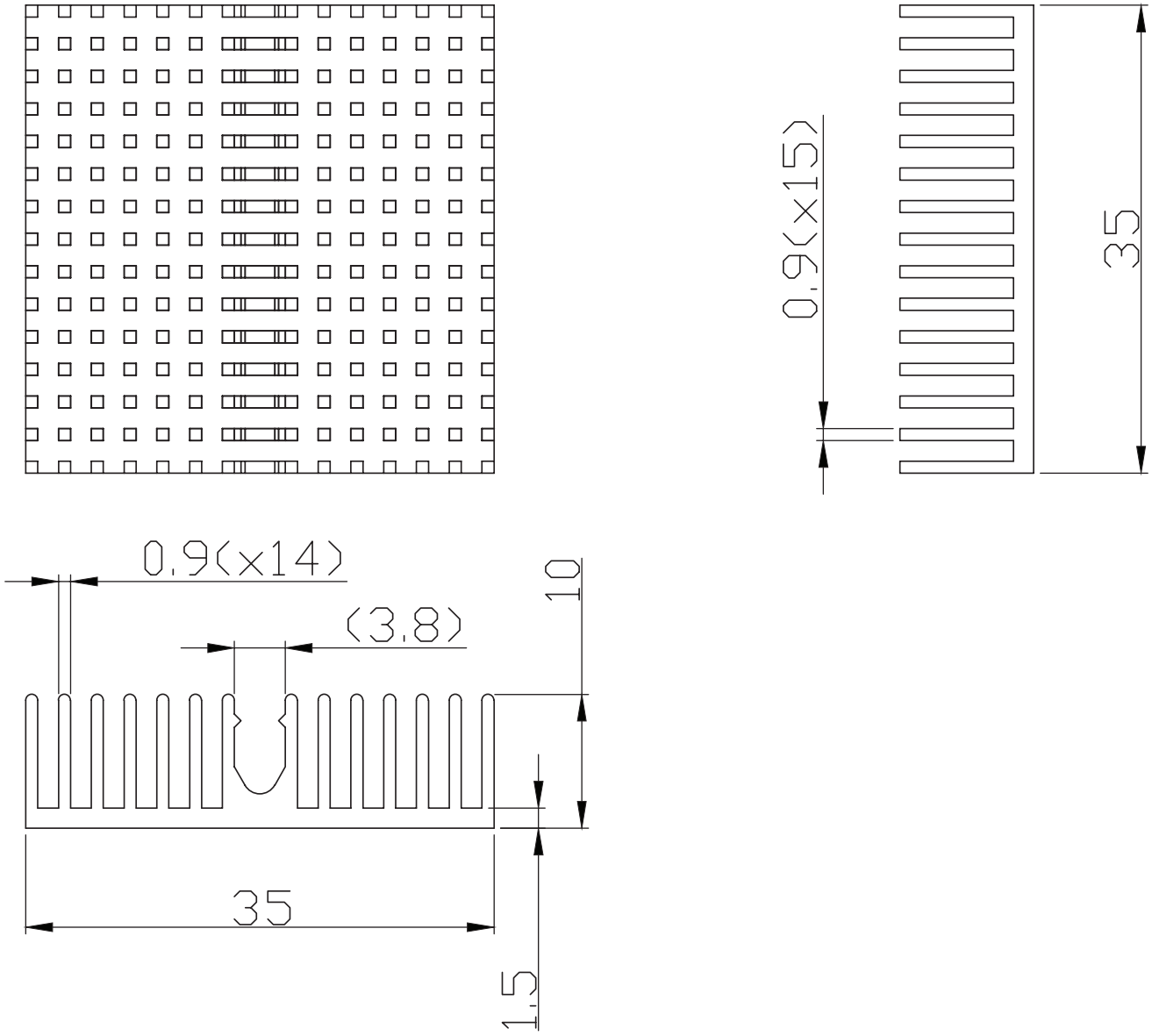
Ths: "hot spot" temperature measured on the heatsink
Ta: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ±0.50 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	11 g



REVISION HISTORY

rev.	description	date
1.0	initial release	03/01/2024
1.01	CUI Devices rebranded to Same Sky	09/12/2024

The revision history provided is for informational purposes only and is believed to be accurate.